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Jan-13-04 11:46am From-Crockett & Crockett

T-784 P.001/003 F-215

Docket No. 212/507

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

In re Application of:

Spiegel, Larry A.

Serial No.: 10/680,995

Art Unit: 3723

Filed: October 7, 2003

For: Improved Retaining Ring
For Wafer Carriers

Examiner: unassigned

REQUEST FOR CORRECTED FILING RECEIPT

Assistant Commissioner For Patents
Office of Initial Patent Examination's
Filing Receipt Corrections
P.O. Box 1450
Alexandria, VA 22313

Fax 703 746 9195

Sir:

Attached is a copy of the official filing receipt dated December 31, 2003 received from the PTO for patent application no. 10/680,995 for which issuance of a corrected filing receipt is respectfully requested. Please correct the error in the "title" of the application as noted on the attachments.

This error incurred through the fault of the United States and Trademark Office and request for the Corrected Filing Receipt should be without charge. Please do not hesitate to contact me should you have any questions.

Date: January 13, 2004

Kristen Truong
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Thank you.



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APPL NO.	FILING OR 371 (C) DATE	ART UNIT	FIL FEE REC'D	ATTY.DOCKET NO	DRAWINGS	TOT CLMS	IND CLMS
10/680,995	10/07/2003	3723	385	212/507	3	17	2

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CONFIRMATION NO. 6656

FILING RECEIPT



OC000000011593059

Date Mailed: 12/31/2003

Receipt is acknowledged of this regular Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Filing Receipt Corrections, facsimile number 703-746-9195. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Larry A. Spiegel, Residence Not Provided;

Assignment For Published Patent Application

Strasbaugh;

Domestic Priority data as claimed by applicant

Foreign Applications

If Required, Foreign Filing License Granted: 12/31/2003

Projected Publication Date: To Be Determined - pending completion of Missing Parts

Non-Publication Request: No

Early Publication Request: No

** SMALL ENTITY **

Title

Improved Retaining ring for wafer carriers

please add 'Improved'

COPY

212/507

Be it known that Larry A. Spiegel has invented a new and useful

Correct title → Improved Retaining Ring for Wafer Carriers

of which the following is a specification:

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Field of the Inventions

The inventions described below relate the field of wafer carriers and particularly to wafer carriers used during optics polishing, prime wafer polishing and chemical mechanical planarization.

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Background of the Inventions

Integrated circuits, including computer chips, are manufactured by building up layers of circuits on the front side of silicon or other semiconductor wafers. An extremely high degree of wafer flatness and layer flatness is required during the manufacturing process. Chemical mechanical planarization (CMP) is a process used during device manufacturing to polish wafers and the layers built-up on wafers to the necessary degree of flatness.

15 Chemical mechanical planarization is a process involving the polishing of a wafer with a polishing pad combined with the chemical and physical action of a slurry pumped onto the pad. The wafer is held by a wafer carrier, with the backside of the wafer facing the wafer carrier and the front side (device side) 20 of the wafer facing a polishing pad. A retaining ring extends downwardly from the outer portion of the wafer carrier and